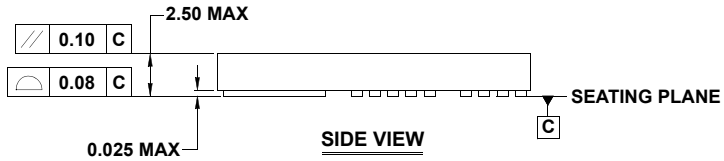
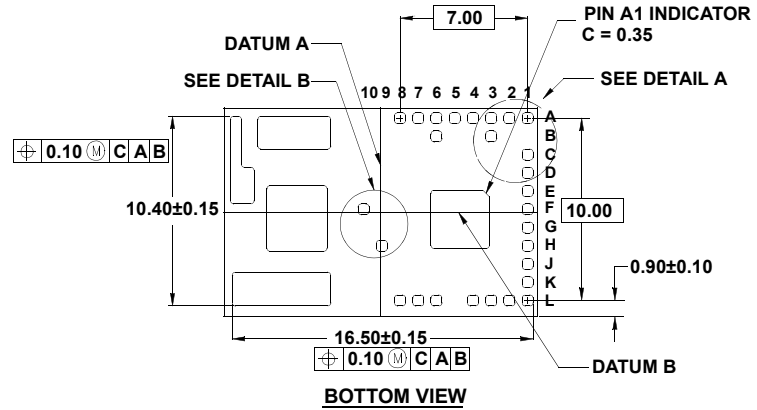
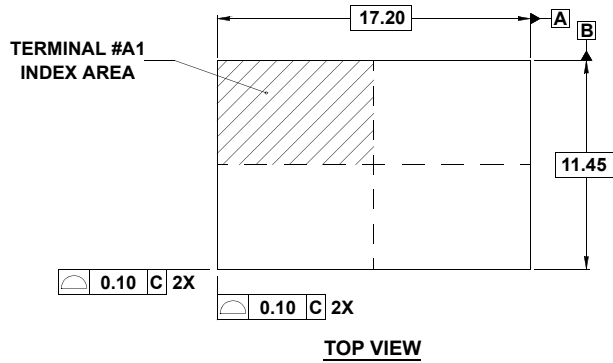


Package Outline Drawing

Y32.17.2x11.45

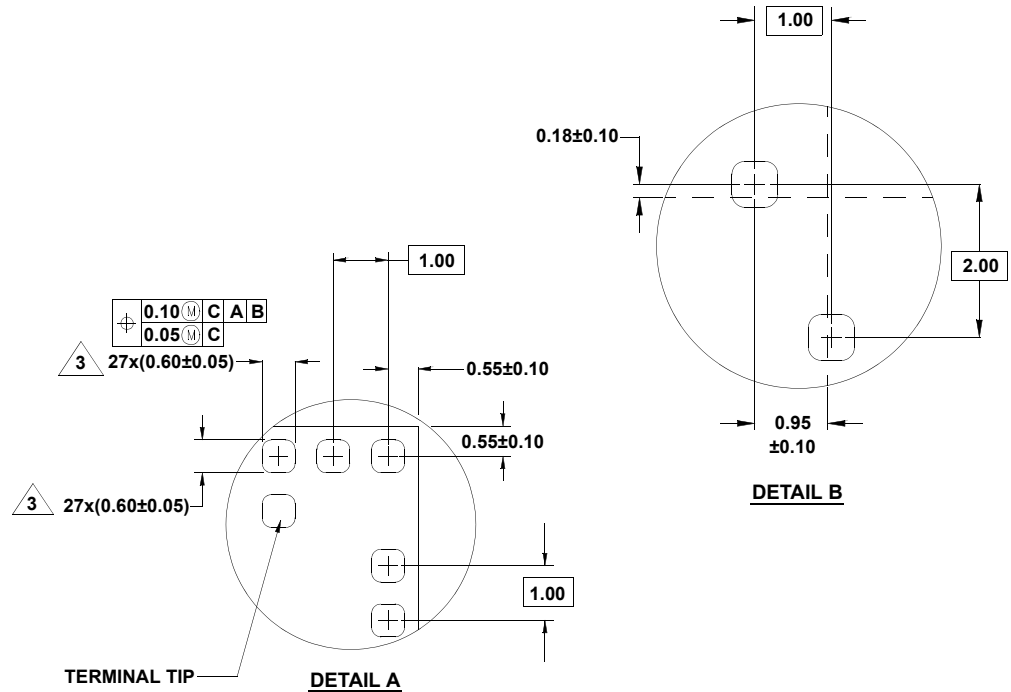
32 I/O 17.2mm x 11.45mm x 2.5mm HDA MODULE

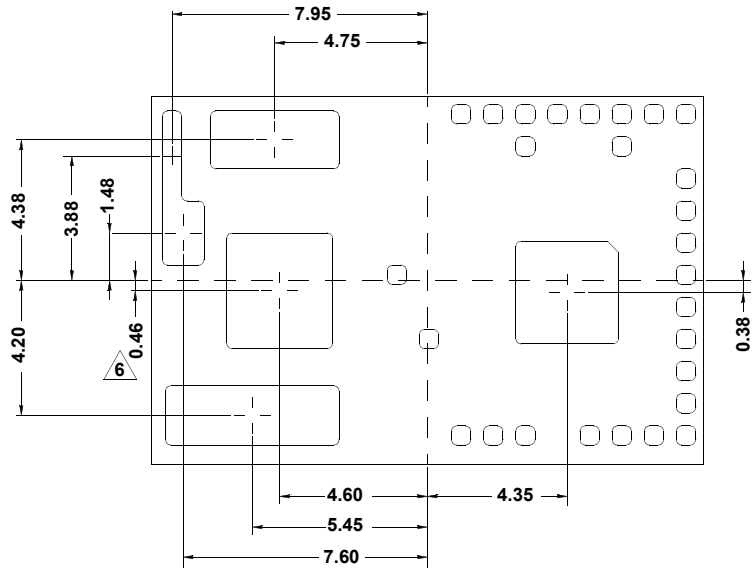
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NOTES:

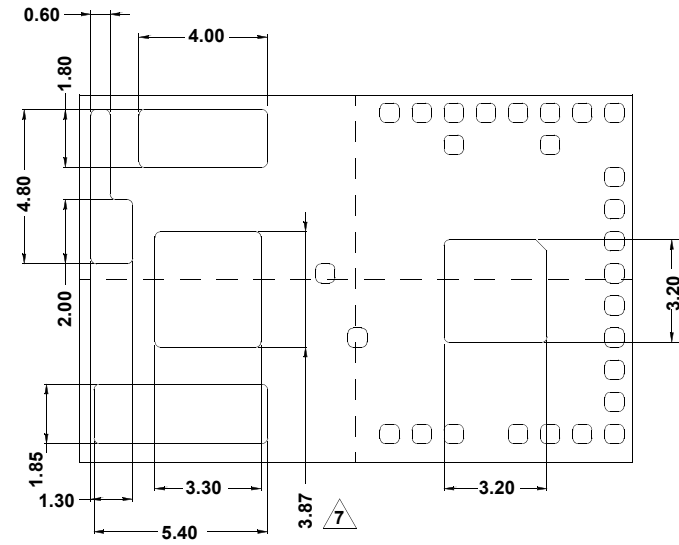
1. All dimensions are in millimeters.
2. 1.0mmx1.0mm represents the basic land grid pitch.
3. "27" is the total number of I/O (excluding large pads). All 27 I/O's are centered in a fixed row and column matrix at 1.0mm pitch BSC.
4. Dimensioning and tolerancing per ASME Y14.5M-1994.
5. Tolerance for exposed DAP edge location dimension on page 2 is ± 0.1 mm.





CENTERLINE POSITION DETAILS FOR THE 5 EXPOSED DAPS

BOTTOM VIEW



SIZE DETAILS FOR THE 5 EXPOSED DAPS

BOTTOM VIEW

NOTES:

- 6. Shown centerline measurement of 0.46mm applies to ZL9006M module. For the ZL9010M module, this measurement is 0.33mm. All other measures identical for both the ZL9006M and ZL9010M modules.
- 7. Shown pad edge measurement of 3.87mm applies to ZL9006M module. For the ZL9010M module, this measurement is 3.60mm. All other measurements are identical for both the ZL9006M and ZL9010M modules.

